

EVALUATION METHOD OF DEVICE WAFER

ABSTRACT

An evaluation method of a device wafer on which plural devices are formed on a front surface and inside which a gettering layer is formed is provided. In the evaluation method, electromagnetic waves are radiated toward a back surface of the device wafer and excitation light is radiated to generate excess carriers. Furthermore, the gettering capability of the gettering layer formed in the device wafer is determined based on the damping time of reflected electromagnetic waves.

(Figure 4)